

INFORMATION DISCLOSURE CITATION  
IN AN APPLICATION

(Use several sheets if necessary)

Docket Number (Optional)

MEGIC-00-001

Application Number

09/684,519

Applicant

J.Y. Lee

Filing Date

10/10/00

Group Art Unit

## U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILED DATE IF APPROPRIATE
HB	6031282	2/29/00	Jones et al.	257	692	8/27/98
HB	6041495	3/28/00	Yoon et al.	29	841	6/1/98
HB	5889652	3/30/99	Turturro	361	705	4/21/97
HB	5990545	11/23/99	Schueller et al.	257	697	12/2/96

## FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

## OTHER DOCUMENTS (Including Author, Title, Date, Portion of Pages, Etc.)

HB	DiStefano et al., "Designing a Modular Chip-Scale Package Assembly Line", Circuit Assembly, March 1977, (pages not numbered). (NO DATE)

EXAMINER

Kyrakin

DATE CONSIDERED

10/16/01

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.